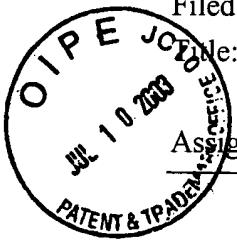


S/N 09/751,614

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Phil Geng et al. Examiner: Jose H. Alcala
Serial No.: 09/751,614 Group Art Unit: 2827
Filed: December 29, 2000 Docket No.: 884.387US1
Title: VIA-IN-PAD WITH OFF-CENTER GEOMETRY AND METHODS OF
MANUFACTURE
Assignee: Intel Corporation



AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants have reviewed the Office Action mailed on May 6, 2003. Please amend the above-identified patent application as follows.